

SOT1175-1

plastic small outline package; 7 leads; body width 3.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO7
Package type industry code	SO7
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	21-4-2010

Table 1. Package summary

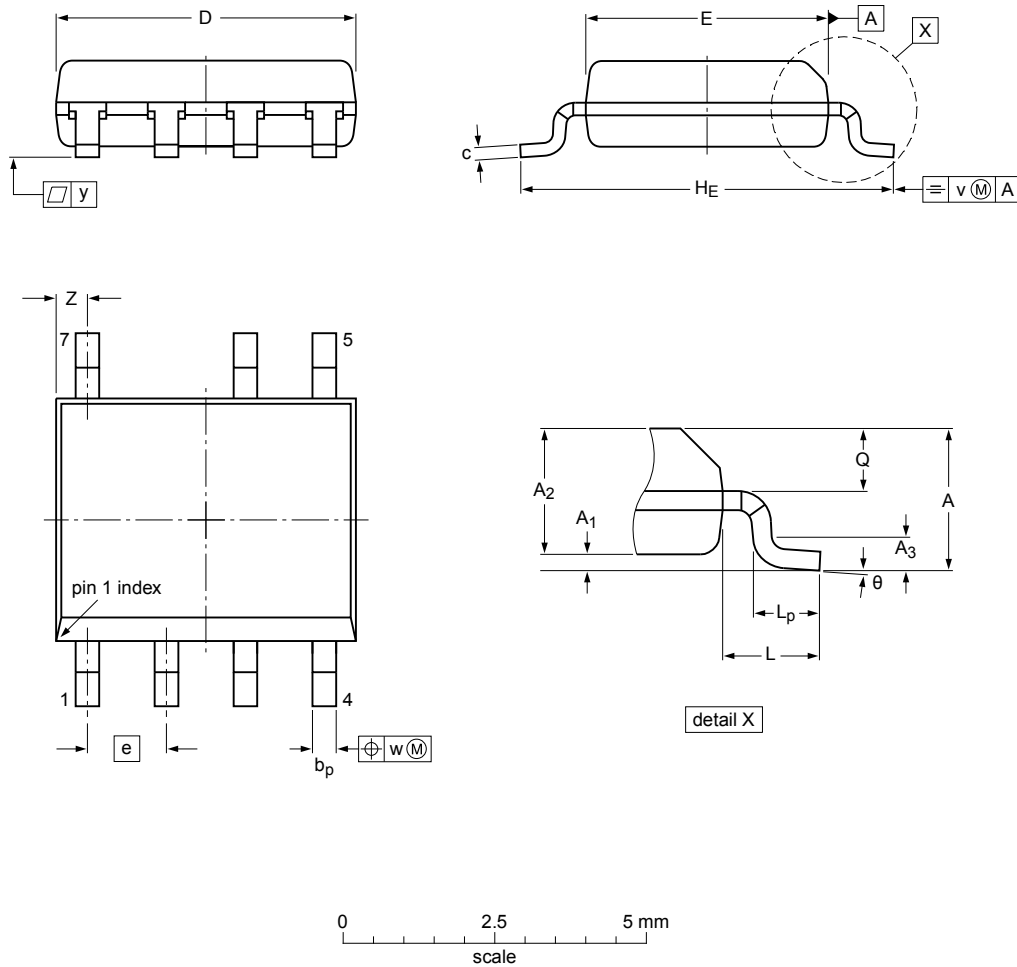
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.8	-	4.9	5	mm
E	package width	3.8	-	3.9	4	mm
A	seated height	[tbd]	-	[tbd]	1.75	mm
A ₂	package height	1.25	-	1.35	1.45	mm
e	nominal pitch	-	-	1.27	-	mm
n ₂	actual quantity of termination	-	-	7	-	



2. Package outline

SOT7: plastic small outline package; 7 leads; body width 3.9 mm

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Dimensions

Unit	A	A ₁	A ₂	A ₃	b _p	c	D	E	e	H _E	L	L _p	Q	v	w	y	Z	θ
max	1.75	0.250	1.45		0.49	0.25	5.0	4.0		6.2		1.0	0.70				0.7	8°
mm nom		0.175	1.35	0.25	0.40	0.20	4.9	3.9	1.27	6.0	1.05	0.7	0.67				0.5	4°
min		0.100	1.25		0.36	0.19	4.8	3.8		5.8		0.4	0.60	0.25	0.25	0.1	0.3	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot1175-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1175-1	---	---	---		10-03-30 10-04-21

Fig. 1. Package outline SOT7 (SOT1175-1)

3. Legal information

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